PhD seminar "Pulse Electrodeposited Copper from Lean Electrolytes"

CURRICUL VITAE

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1 Short CV

I completed my BTech in Chemical Engineering from the Indian Institute of Technology, Delhi in 1985. After working in India for just over a year I studied for MS (1990) and PhD degrees (1992) in Chemical Engineering from Tulane University in the USA. I then spent nearly three years as postdoctoral scientist at the materials department in EPFL in Switzerland, before moving to Newcastle University in the UK in 1994 to take up a position as lecturer in Chemical Engineering. I was promoted to Reader in 2000 and then to a personal chair in Electrochemical Nanomaterials in 2005. In 2015 I moved to the University of Strathclyde where I am currently Professor of Chemical Engineering and Head of Department. I am a Fellow of the IChemE, IMF and a Chartered Engineer.

2 Bibliometric data

Over 90 publications as refereed journal articles and 150 other forms of dissemination. Currently lead a research group of 8-9 members, including 3 academic staff. H-index 26 and 1770 citations on Scopus.

3 Selection of the 10 most relevant publications and/or patents

Electrochemical copper recovery from galvanic sludge
Huyen, P. T., Dang, T. D., Tung, M. T., Huyen, N. T. T., Green, T. A. & Roy, S.
Hydrometallurgy. 164, p. 295-303 9 p. (2016)

Characteristics of anode materials for nickel electroforming
Green Todd, Tambe Christine Enowmbi, Roy Sudipta
Journal of the Electrochemical Society Vol 169 (2022)

Effect of additive concentration during copper deposition using EnFACE electrolyte
Dela Pena, E. M., Bains, N., Hussain, A., Cobley, A. & Roy, S.
Transactions of the Institute of Metal Finishing. 93, 6, p. 288-293 6 p. (2015)

Modelling the electroforming process : significance and challenges
Andreou Eleni, Roy Sudipta
Transactions of the Institute of Metal Finishing Vol 99, pp. 299-305 (2021)

Pulse electrodeposition of copper in the presence of a corrosion reaction
Green TA, Su X, Roy S
Journal of the Electrochemical Society Vol 168 (2021)

Application of a duplex diffusion layer model to pulse reverse plating
Green, T. A. & Roy, S.
Transactions of the Institute of Metal Finishing. 95, 1, p. 46-51 6 p. (2017)

Effect of water on the electrodeposition of copper from a deep eutectic solvent
Valverde, P. E., Green, T. A. & Roy, S.,
Journal of Applied Electrochemistry. 50, 6, p. 699-712 14 p (2020)

Voltammetric response of water in deep eutectic solvent based on choline chloride and urea
Bučko, M., Roy, S., Valverde-Armas, P., Onjia, A., Bastos, A. C. & Bajat, J. B.
Journal of the Electrochemical Society. 165, 16, p. H1059-H1065 7 p. (2018)

Anodic reactions and the corrosion of copper in deep eutectic solvents
Green, T. A., Valverde, P. & Roy, S.
Journal of the Electrochemical Society. 165, 9, p. D313-D320 8 p.(2018)

Copper electrodeposition from a water-containing choline chloride based deep eutectic solvent
Valverde, P., Green, T. & Roy, S.
ECS Transactions. 77, 11, p. 859-864 6 p. (2017)